

# SSM6P09FU

## High Speed Switching Applications

- Small package
- Low Drain-Source ON resistance.
  - :  $R_{on} = 2.7 \Omega$  (max) (@ $V_{GS} = -10 V$ )
  - :  $R_{on} = 4.2 \Omega$  (max) (@ $V_{GS} = -4 V$ )

## Absolute Maximum Ratings (Ta = 25°C) (Q1, Q2 Common)

| Characteristics                     | Symbol         | Rating   | Unit |
|-------------------------------------|----------------|----------|------|
| Drain-Source voltage                | $V_{DS}$       | -30      | V    |
| Gate-Source voltage                 | $V_{GSS}$      | $\pm 20$ | V    |
| Drain current                       | DC             | $I_D$    | -200 |
|                                     | Pulse          | $I_{DP}$ | -800 |
| Drain power dissipation (Ta = 25°C) | $P_D$ (Note 1) | 300      | mW   |
| Channel temperature                 | $T_{ch}$       | 150      | °C   |
| Storage temperature range           | $T_{stg}$      | -55~150  | °C   |

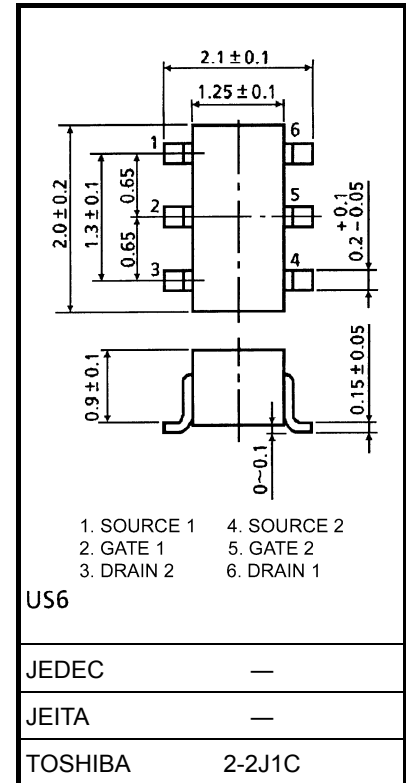
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Total rating, mounted on FR4 board  
(25.4 mm × 25.4 mm × 1.6 t, Cu Pad: 0.32 mm<sup>2</sup> × 6) Figure 1.

## Handling Precaution

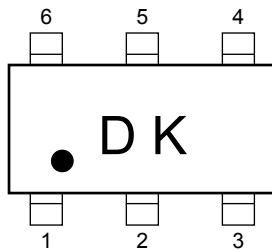
When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

Unit: mm



Weight: 6.8 mg (typ.)

## Marking



## Equivalent Circuit (top view)

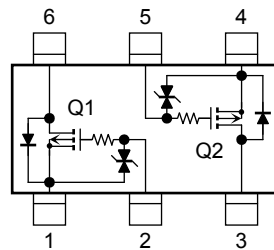
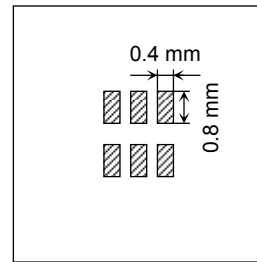


Figure 1: 25.4 mm × 25.4 mm × 1.6 t, Cu Pad: 0.32 mm<sup>2</sup> × 6



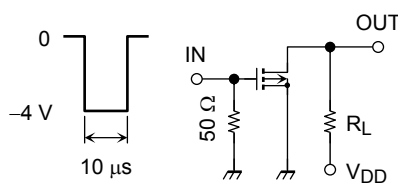
## Electrical Characteristics (Ta = 25°C) (Q1, Q2 common)

| Characteristics                | Symbol        | Test Condition   | Min  | Typ. | Max     | Unit          |
|--------------------------------|---------------|--|------|------|---------|---------------|
| Gate leakage current           | $I_{GSS}$     | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$                                      | —    | —    | $\pm 1$ | $\mu\text{A}$ |
| Drain-Source breakdown voltage | $V_{(BR)DSS}$ | $I_D = -1 \text{ mA}, V_{GS} = 0$  | -30  | —    | —       | V             |
| Drain cut-off current          | $I_{DSS}$     | $V_{DS} = -30 \text{ V}, V_{GS} = 0$   | —    | —    | -1      | $\mu\text{A}$ |
| Gate threshold voltage         | $V_{th}$      | $V_{DS} = -5 \text{ V}, I_D = -0.1 \text{ mA}$                               | -1.1 | —    | -1.8    | V             |
| Forward transfer admittance    | $ Y_{fs} $    | $V_{DS} = -5 \text{ V}, I_D = -100 \text{ mA}$ (Note2)                       | 115  | —    | —       | mS            |
| Drain-Source ON resistance     | $R_{DS(ON)}$  | $I_D = -100 \text{ mA}, V_{GS} = -10 \text{ V}$ (Note2)                      | —    | 2.1  | 2.7     | $\Omega$      |
|                                |               | $I_D = -100 \text{ mA}, V_{GS} = -4 \text{ V}$ (Note2)                       | —    | 3.3  | 4.2     |               |
|                                |               | $I_D = -100 \text{ mA}, V_{GS} = -3.3 \text{ V}$ (Note2)                     | —    | 4.0  | 6.0     |               |
| Input capacitance              | $C_{iss}$     | $V_{DS} = -5 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$                       | —    | 22   | —       | pF            |
| Reverse transfer capacitance   | $C_{rss}$     | $V_{DS} = -5 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$                       | —    | 5    | —       | pF            |
| Output capacitance             | $C_{oss}$     | $V_{DS} = -5 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$                       | —    | 14   | —       | pF            |
| Switching time                 | Turn-on time  | $t_{on}$   | —    | 85   | —       | ns            |
|                                | Turn-off time | $t_{off}$  |      |      |         |               |
|                                |               | $V_{DD} = -5 \text{ V}, I_D = -100 \text{ mA}, V_{GS} = 0 \sim -4 \text{ V}$ |      |      |         |               |

Note2: Pulse test

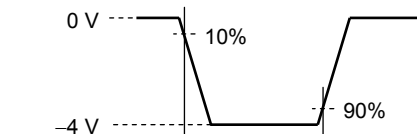
## Switching Time Test Circuit (Q1, Q2 Common)

### (a) Test circuit

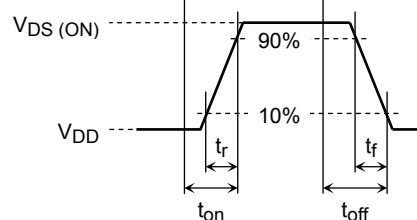


$V_{DD} = -5 \text{ V}$   
 Duty  $\leq 1\%$   
 $V_{IN}$ :  $t_r, t_f < 5 \text{ ns}$   
 ( $Z_{out} = 50 \Omega$ )  
 Common Source  
 $T_a = 25^\circ\text{C}$

### (b) $V_{IN}$



### (c) $V_{OUT}$

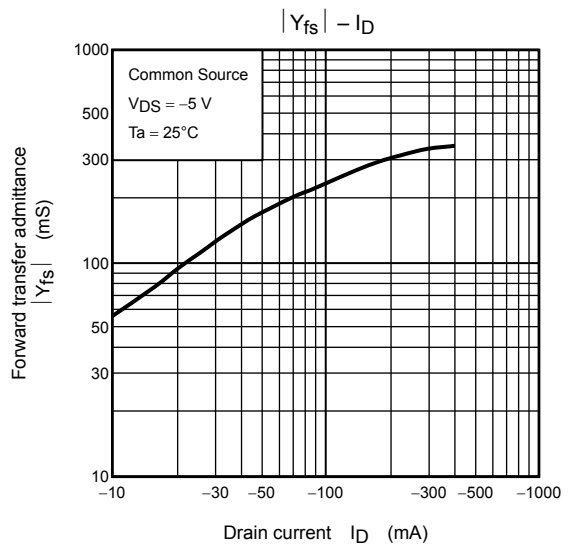
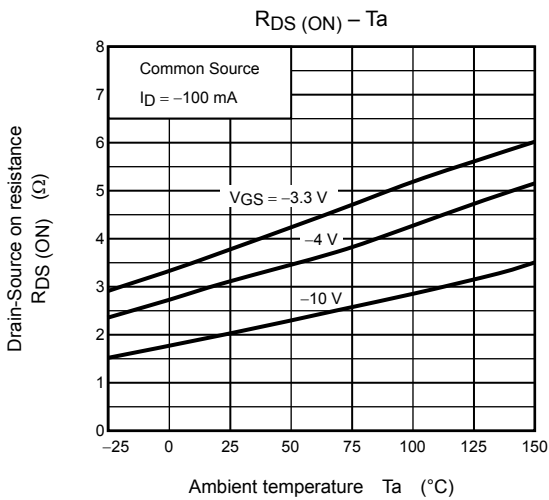
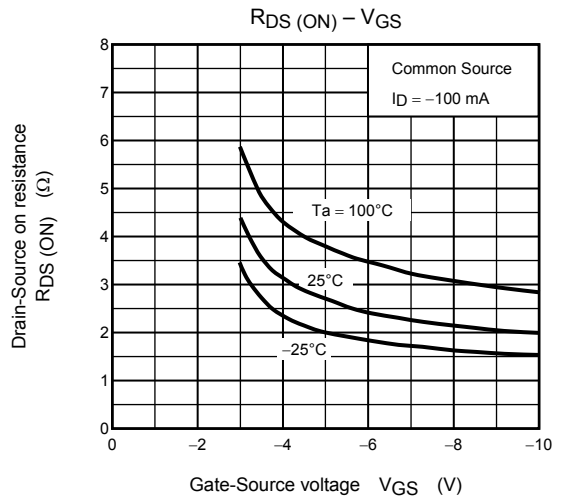
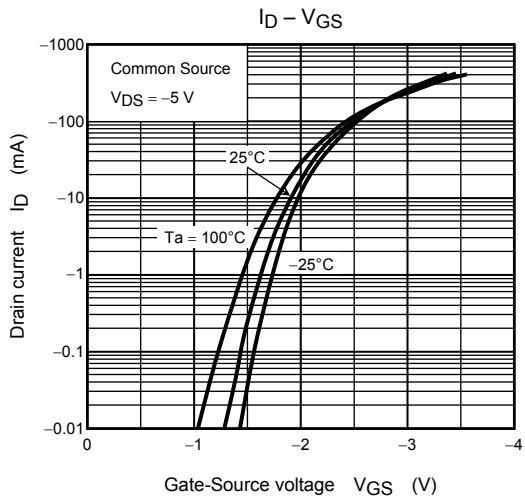
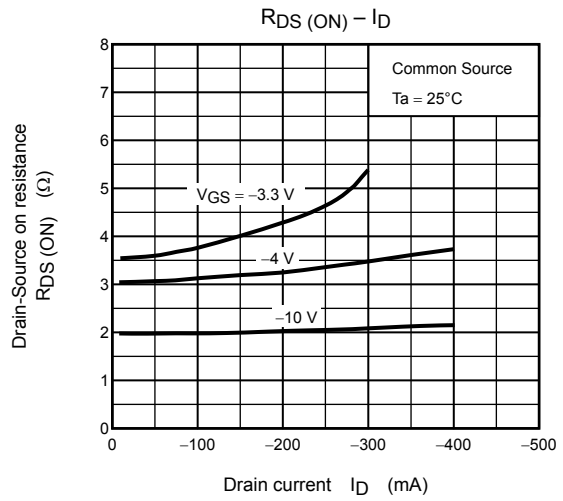
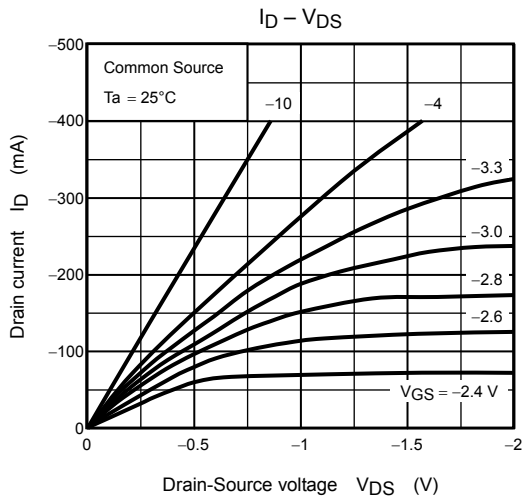


## Precaution

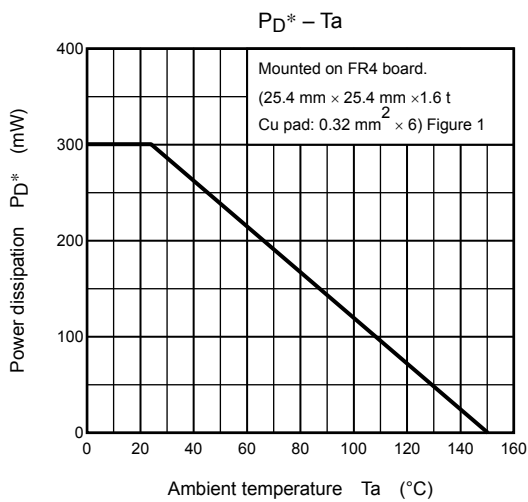
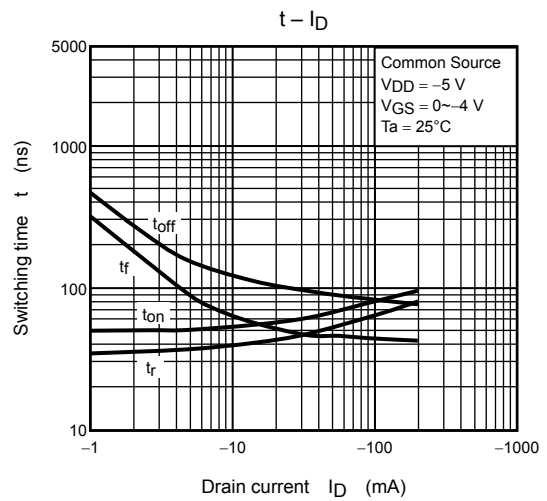
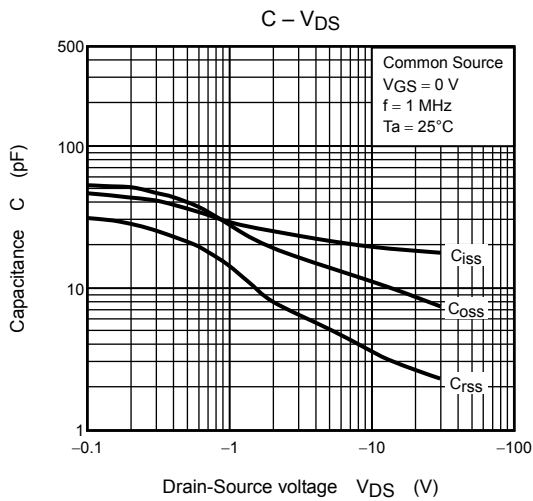
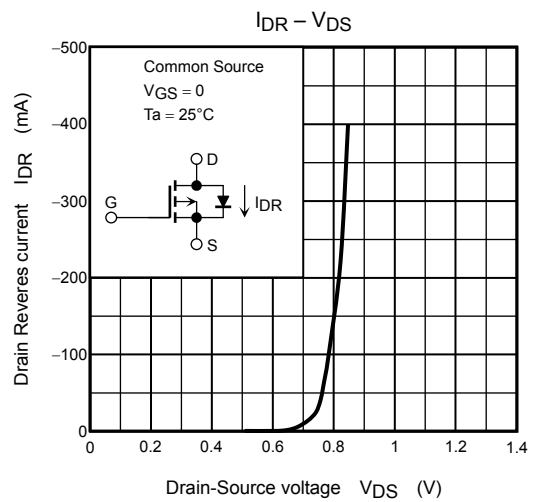
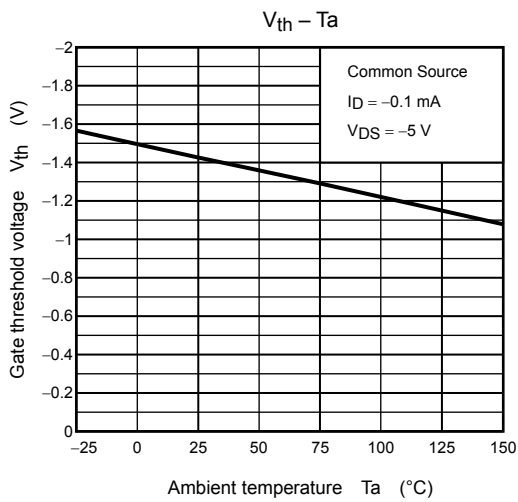
$V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D = -100 \mu\text{A}$  for this product. For normal switching operation,  $V_{GS(on)}$  requires higher voltage than  $V_{th}$  and  $V_{GS(off)}$  requires lower voltage than  $V_{th}$ . (Relationship can be established as follows:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ )

Please take this into consideration for using the device.

(Q1, Q2 common)



(Q1, Q2 common)



\*: Total rating

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